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a conductive connecting member disposed between the board wiring pad and the element wiring pad.

167. The surface acoustic wave device as set forth in Claim 166, wherein a difference between a thickness of the board wiring pattern and a thickness of the board wiring pad is in the range of from 5 μm to 100 μm .

168. A surface acoustic wave device, comprising:

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a printed circuit board possessing a first region and a second region which is larger in thickness than the first region, the second region including a board wiring pad;

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a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring pad and a surface acoustic wave absorbing member, and being disposed with a face-down arrangement so that the surface acoustic wave absorbing member is disposed in an opposite relation with respect to the first region of the printed circuit board; and

a conductive connecting member disposed between the board wiring pad and the element wiring pad.

169. The surface acoustic wave device as set forth in Claim 168 wherein a difference between a thickness of the first region and a thickness of the second region of the printed circuit board is in the range of from 5 μm to 500 μm .

170. A surface acoustic wave device, comprising:

a printed circuit board possessing a first board surface and a second board surface, the first board surface having a board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring pad and a